

300 mA LDO REGULATOR

No.EA-236-190130

OUTLINE

The RP114x is a CMOS-based voltage regulator IC with high output voltage accuracy, low supply current, low dropout, and high ripple rejection. This IC consists of a voltage reference unit, an error amplifier, resistors for setting output voltage, a short current limit circuit, a chip enable circuit, and so on. The RP114x features a minimum input voltage from 1.4V and the output voltage, which can be set from 0.8V to 3.6V (in 0.1V step). The output voltage of this IC is internally fixed. This IC perform with low dropout voltage due to built-in transistor with low ON resistance. Low supply current and a chip enable function prolong the battery life of each system. The ripple rejection, line transient response and load transient response of the RP114x is excellent, thus this IC is very suitable for the power supply for hand-held communication equipment. Since the packages for this IC are DFN(PLP)1010-4、DFN(PLP)1010-4B、SC-88A、SOT-23-5, therefore high density mounting of the IC on boards is possible.

FEATURES

- Supply Current..... Typ. 50 μ A
- Standby Current Typ. 0.1 μ A
- Input Voltage Range 1.4V to 5.25V
- Output Voltage Range⁽¹⁾ 0.8V to 3.6V (0.1V steps)
- Output Voltage Accuracy $\pm 1.0\%$ ($V_{SET} > 2.0V$, $T_a = 25^\circ C$)
- Temperature-Drift Coefficient of Output Voltage..... Typ. $\pm 80ppm/^\circ C$
- Dropout Voltage..... Typ. 0.25V ($I_{OUT} = 300mA$, $V_{SET} = 2.8V$)
- Ripple Rejection Typ. 75dB ($f = 1kHz$)
- Line Regulation..... Typ. 0.02%/V
- Packages DFN(PLP)1010-4、DFN(PLP)1010-4B、SC-88A、SOT-23-5
- Built-in Fold Back Protection Circuit Typ. 60mA (Current at short mode)
- Ceramic capacitors are recommended to be used with this IC 1.0 μ F or more

APPLICATIONS

- Power source for portable communication equipment.
- Power source for electrical appliances such as cameras, VCRs and camcorders.
- Power source for battery-powered equipment.

⁽¹⁾ For other voltages, please refer to *Product-specific Electrical Characteristics*.

RP114x

No.EA-236-190130

SELECTION GUIDE

The set output voltage, the auto discharge function⁽¹⁾, and the package type for the ICs are user-selectable options.

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free
RP114Kxx1*(y)-TR	DFN(PLP)1010-4	10,000 pcs	Yes	Yes
RP114Kxx1*(y)-TRB	DFN(PLP)1010-4B	10,000 pcs	Yes	Yes
RP114Qxx2*(y)-TR-FE	SC-88A	3,000 pcs	Yes	Yes
RP114Nxx1*(y)-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes

xx: Specify the set output voltage within the range of 0.8 V (08) to 3.6 V (36) in 0.1 V step.

(y): If the output voltage includes the 3rd digit, indicate the digit of 0.01V.

Ex. If the output voltage is 1.25V, RP114K121*5-TR

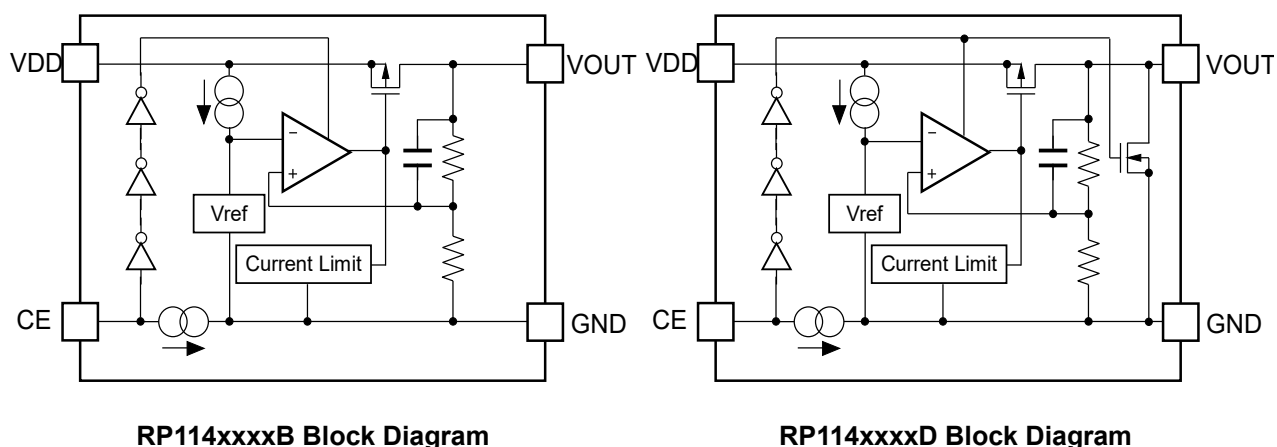
If the output voltage is 1.85V, RP114K181*5-TR

*: Specify a combination of the CE pin polarity and the auto-discharge function.

(B) "H" Active, without Auto-Discharge function

(D) "H" Active, with Auto-Discharge function

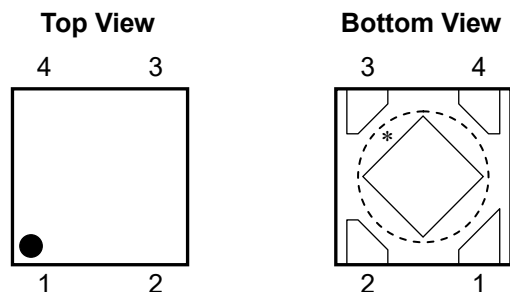
BLOCK DIAGRAMS



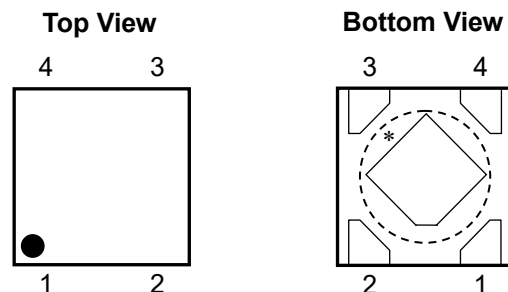
⁽¹⁾ Auto-Discharge function quickly lowers the output voltage to 0V by releasing the electrical charge in the external capacitor when the chip enable signal is switched from the active mode to the standby mode.

PIN DESCRIPTIONS

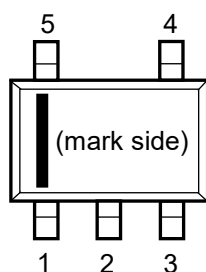
RP114K [DFN(PLP)1010-4]



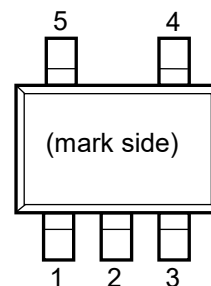
RP114K [DFN(PLP)1010-4B]



RP114Q (SC-88A)



RP114N (SOT-23-5)



RP114K Pin Description [DFN(PLP)1010-4 / DFN(PLP)1010-4B]

Pin No	Symbol	Pin Description
1	VOUT	Output Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	VDD	Input Pin

* Tab is GND level. (They are connected to the reverse side of this IC.) The tab is better to be connected to the GND, but leaving it open is also acceptable.

RP114Q Pin Description (SC-88A)

Pin No	Symbol	Description
1	CE	Chip Enable Pin ("H" Active)
2	NC	No Connection
3	GND	Ground Pin
4	VOUT	Output Pin
5	VDD	Input Pin

RP114x

No.EA-236-190130

RP114N Pin Description (SOT-23-5)

Pin No	Symbol	Description
1	VDD	Input Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin ("H" Active)
4	NC	No Connection
5	VOUT	Output Pin

ABSOLUTE MAXIMUM RATINGS

Symbol	Item		Rating	Unit
V_{IN}	Input Voltage		6.0	V
V_{CE}	Input Voltage (CE Pin)		6.0	V
V_{OUT}	Output Voltage		-0.3 to $V_{IN}+0.3$	V
I_{OUT}	Output Current		400	mA
P_D	Power Dissipation ⁽¹⁾	DFN(PLP)1010-4, JEDEC STD. 51	800	mW
		DFN(PLP)1010-4B, JEDEC STD. 51	800	
		SC-88A, Our Evaluation Board	380	
		SOT-23-5, JEDEC STD. 51	660	
T_j	Junction Temperature Range		-40 to 125	°C
T_{stg}	Storage Temperature Range		-55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause the permanent damages and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings are not assured.

RECOMMENDED OPERATING CONDITIONS

Symbol	Item	Rating	Unit
V_{IN}	Input Voltage	1.4 to 5.25 ⁽²⁾	V
T_a	Operating Temperature Range	-40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if when they are used over such ratings by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽¹⁾ Refer to *POWER DISSIPATION* for detailed information.

⁽²⁾ If the input voltage exceeds the maximum value of 5.25 V for some reasons, the operational accumulated time becomes up to 500 hours at 5.5V.

RP114x

No.EA-236-190130

ELECTRICAL CHARACTERISTICS

$V_{IN} = V_{SET}^{(1)} + 1.0 \text{ V}$ ($V_{SET} > 1.5 \text{ V}$), $V_{IN} = 2.5 \text{ V}$ ($V_{SET} \leq 1.5 \text{ V}$), $I_{OUT} = 1 \text{ mA}$, $C_{IN} = C_{OUT} = 1.0 \mu\text{F}$, unless otherwise noted.

The specifications in are guaranteed by design engineering at $-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$.

RP114xxxxB/D Electrical Characteristics

($T_a = 25^\circ\text{C}$)

Symbol	Item	Conditions	Min.	Typ.	Max.	Unit
V_{OUT}	Output Voltage	$T_a = 25^\circ\text{C}$	$V_{SET} > 2.0 \text{ V}$	$\times 0.99$	$\times 1.01$	V
			$V_{SET} \leq 2.0 \text{ V}$	-20	+20	mV
		$-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$	$V_{SET} > 2.0 \text{ V}$	$\times 0.97$	$\times 1.03$	V
			$V_{SET} \leq 2.0 \text{ V}$	-60	+60	mV
I_{OUT}	Output Current		300			mA
$\Delta V_{OUT}/\Delta I_{OUT}$	Load Regulation	$1 \text{ mA} \leq I_{OUT} \leq 300 \text{ mA}$		15	40	mV
V_{DIF}	Dropout Voltage	Please refer to <i>Product-specific Electrical Characteristics</i> attached.				
I_{SS}	Supply Current	$I_{OUT} = 0 \text{ mA}$		50	75	μA
$I_{standby}$	Standby Current	$V_{CE} = 0 \text{ V}$		0.1	1.0	μA
$\Delta V_{OUT}/\Delta V_{IN}$	Line Regulation	$V_{SET} + 0.5 \text{ V} \leq V_{IN} \leq 5.25 \text{ V}$ ($V_{IN} \geq 1.4 \text{ V}$)		0.02	0.10	%/V
R_R	Ripple Rejection	$f = 1 \text{ kHz}$, Ripple 0.2 V_{p-p} , $V_{IN} = V_{SET} + 1 \text{ V}$, $I_{OUT} = 30 \text{ mA}$ (When $V_{SET} \leq 2.0 \text{ V}$, $V_{IN} = 3.0 \text{ V}$)		75		dB
$\Delta V_{OUT}/\Delta T_a$	Output Voltage Temperature Coefficient	$-40^\circ\text{C} \leq T_a \leq 85^\circ\text{C}$		± 80		ppm/ $^\circ\text{C}$
I_{SC}	Short Current Limit	$V_{OUT} = 0 \text{ V}$		60		mA
I_{PD}	CE Pull-down Current			0.3	0.6	μA
V_{CEH}	CE Input Voltage "H"		1.0			V
V_{CEL}	CE Input Voltage "L"				0.4	V
e_n	Output Noise	$BW = 10 \text{ Hz to } 100 \text{ kHz}$, $I_{OUT} = 30 \text{ mA}$		75		μV_{rms}
R_{LOW}	Low Output Nch. On Resistance (RP114xxxxD Only)	$V_{IN} = 4.0 \text{ V}$, $V_{CE} = 0 \text{ V}$		50		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition ($T_j \approx T_a = 25^\circ\text{C}$) except for Output Noise, Ripple Rejection, and Output Voltage Temperature Coefficient.

⁽¹⁾ V_{SET} : Set Output Voltage

The specifications in are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$.

Dropout Voltage by Set Output Voltage

(Ta=25°C)

Set Output Voltage V_{SET} (V)	Dropout Voltage V_{DIF} (V)		
	Condition	Typ.	Max.
$V_{\text{SET}}=0.8$	$I_{\text{OUT}}=300\text{mA}$	0.560	0.720
$V_{\text{SET}}=0.9$		0.510	0.650
$1.0 \leq V_{\text{SET}} < 1.2$		0.460	0.590
$1.2 \leq V_{\text{SET}} < 1.4$		0.390	0.500
$1.4 \leq V_{\text{SET}} < 1.7$		0.350	0.440
$1.7 \leq V_{\text{SET}} < 2.1$		0.300	0.390
$2.1 \leq V_{\text{SET}} < 2.5$		0.260	0.340
$2.5 \leq V_{\text{SET}} < 3.0$		0.250	0.300
$3.0 \leq V_{\text{SET}} \leq 3.6$		0.220	0.290

RP114x

No.EA-236-190130

Product-specific Electrical Characteristics

The specifications in are guaranteed by design engineering at $-40^{\circ}\text{C} \leq T_a \leq 85^{\circ}\text{C}$.

Product Name	V _{OUT} [V] (Ta = 25°C)			V _{OUT} [V] (-40°C ≤ Ta ≤ 85°C)			V _{DIF} [V]	
	Min.	Typ.	Max.	Min.	Typ.	Max.	Typ.	Max.
RP114x081x	0.780	0.800	0.820	0.740	0.800	0.860	0.560	0.720
RP114x091x	0.880	0.900	0.920	0.840	0.900	0.960	0.510	0.650
RP114x101x	0.980	1.000	1.020	0.940	1.000	1.060	0.460	0.590
RP114x101x5	1.030	1.050	1.070	0.990	1.050	1.110		
RP114x111x	1.080	1.100	1.120	1.040	1.100	1.160		
RP114x111x5	1.130	1.150	1.170	1.090	1.150	1.210		
RP114x121x	1.180	1.200	1.220	1.140	1.200	1.260	0.390	0.500
RP114x121x5	1.230	1.250	1.270	1.190	1.250	1.310		
RP114x131x	1.280	1.300	1.320	1.240	1.300	1.360		
RP114x131x5	1.330	1.350	1.370	1.290	1.350	1.410		
RP114x141x	1.380	1.400	1.420	1.340	1.400	1.460	0.350	0.440
RP114x151x	1.480	1.500	1.520	1.440	1.500	1.560		
RP114x161x	1.580	1.600	1.620	1.540	1.600	1.660		
RP114x171x	1.680	1.700	1.720	1.640	1.700	1.760	0.300	0.390
RP114x171x5	1.730	1.750	1.770	1.690	1.750	1.810		
RP114x181x	1.780	1.800	1.820	1.740	1.800	1.860		
RP114x181x5	1.830	1.850	1.870	1.790	1.850	1.910		
RP114x191x	1.880	1.900	1.920	1.840	1.900	1.960	0.260	0.340
RP114x201x	1.980	2.000	2.020	1.940	2.000	2.060		
RP114x211x	2.079	2.100	2.121	2.037	2.100	2.163		
RP114x221x	2.178	2.200	2.222	2.134	2.200	2.266		
RP114x231x	2.277	2.300	2.323	2.231	2.300	2.369	0.250	0.300
RP114x241x	2.376	2.400	2.424	2.328	2.400	2.472		
RP114x251x	2.475	2.500	2.525	2.425	2.500	2.575		
RP114x261x	2.574	2.600	2.626	2.522	2.600	2.678		
RP114x271x	2.673	2.700	2.727	2.619	2.700	2.781	0.220	0.290
RP114x281x	2.772	2.800	2.828	2.716	2.800	2.884		
RP114x281x5	2.822	2.850	2.879	2.765	2.850	2.936		
RP114x291x	2.871	2.900	2.929	2.813	2.900	2.987		
RP114x301x	2.970	3.000	3.030	2.910	3.000	3.090	0.220	0.290
RP114x311x	3.069	3.100	3.131	3.007	3.100	3.193		
RP114x321x	3.168	3.200	3.232	3.104	3.200	3.296		
RP114x331x	3.267	3.300	3.333	3.201	3.300	3.399		
RP114x341x	3.366	3.400	3.434	3.298	3.400	3.502	0.220	0.290
RP114x341x5	3.416	3.450	3.485	3.347	3.450	3.554		
RP114x351x	3.465	3.500	3.535	3.395	3.500	3.605		
RP114x361x	3.564	3.600	3.636	3.492	3.600	3.708		

TEST CIRCUITS

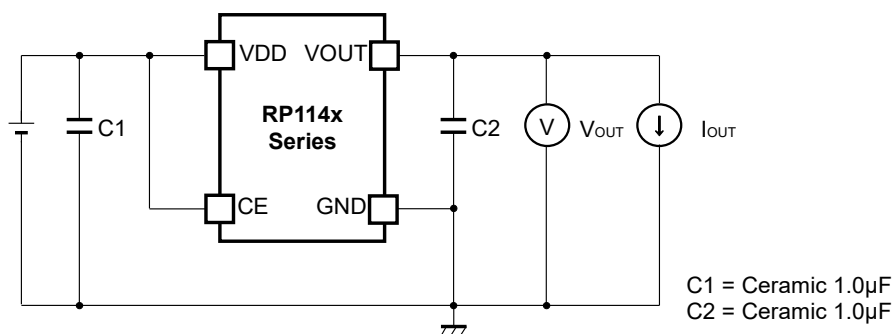


Figure 1. Basic Test Circuit

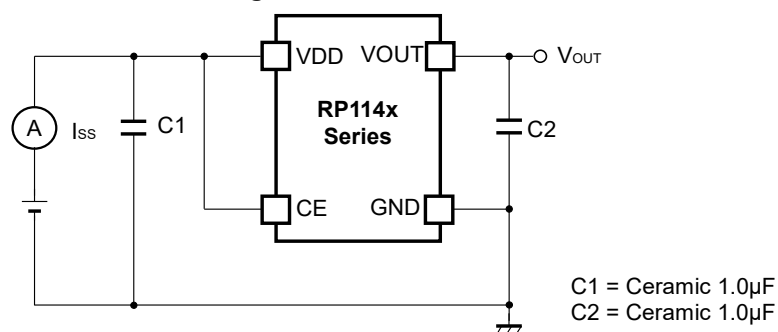


Figure 2. Test Circuit for Supply Current

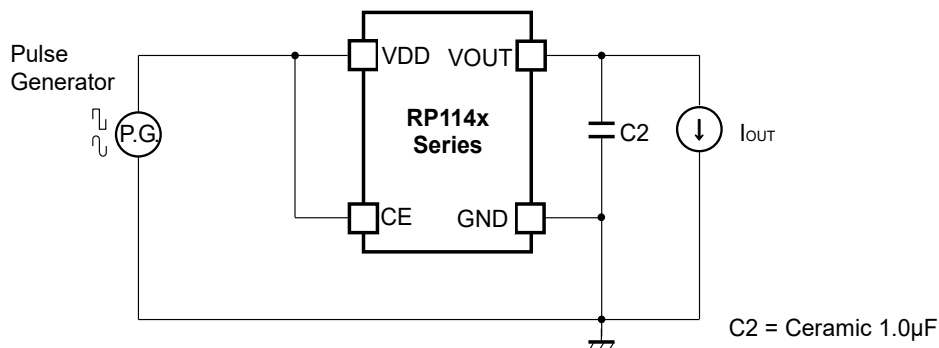


Figure 3. Test Circuit for Ripple Rejection

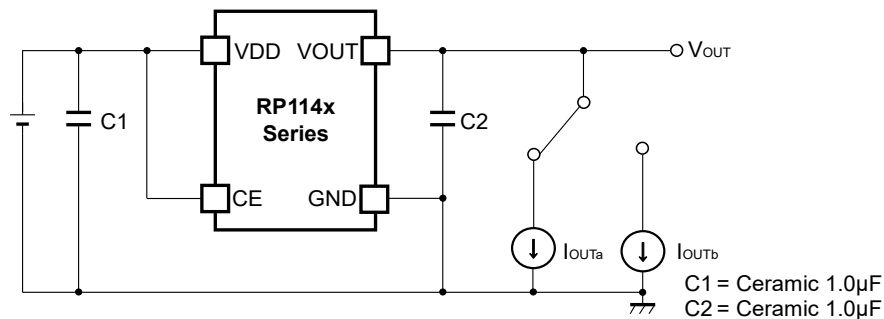


Figure 4. Test Circuit for Load Transient Response

TECHNICAL NOTES ON EXTERNAL COMPONENTS

When using these ICs, consider the following points:

Phase Compensation

In this IC, phase compensation is made for securing stable operation even if the load current is varied. For this purpose, use a capacitor C2 with 1.0 μ F or more and good ESR (Equivalent Series Resistance).

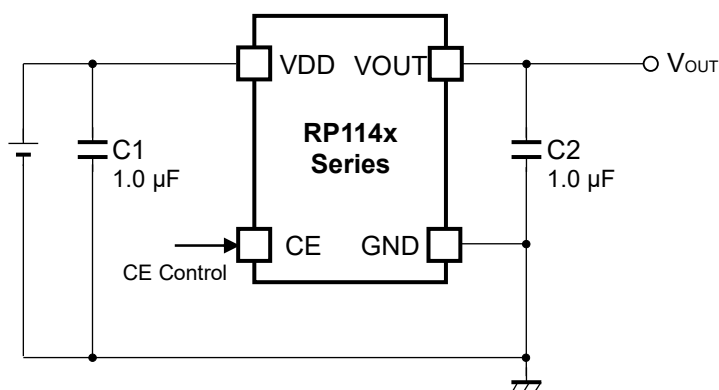
(Note: If additional ceramic capacitors are connected with parallel to the output pin with an output capacitor for phase compensation, the operation might be unstable. Because of this, test this IC with as same external components as ones to be used on the PCB.)

PCB Layout

Make V_{DD} and GND lines sufficient. If their impedance is high, noise pickup or unstable operation may result. Connect a capacitor C1 with a capacitance value as much as 1.0 μ F or more between VDD and GND pins, and as close as possible to the pins.

Set external components, especially the output capacitor C2, as close as possible to the IC, and make wiring as short as possible.

Typical Application Circuit



ESR vs. Output Current

When using these ICs, consider the following points:

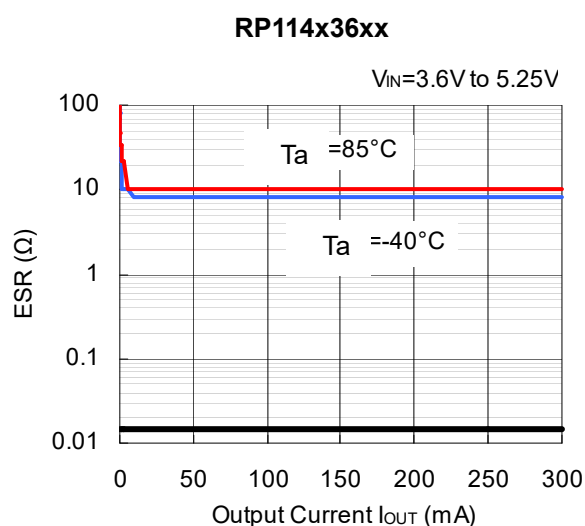
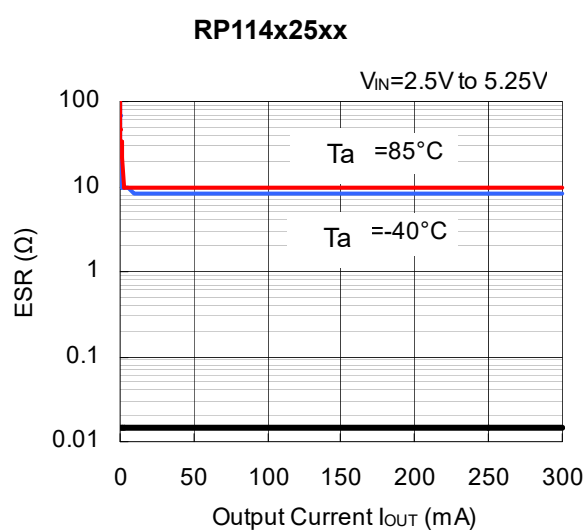
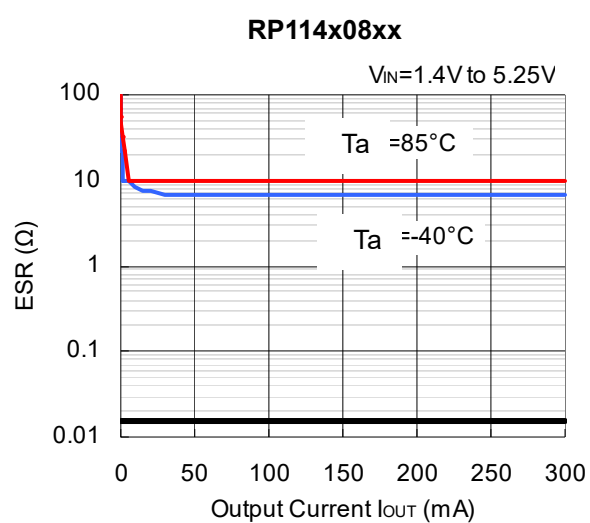
The relations between I_{OUT} (Output Current) and ESR of an output capacitor are shown below. The conditions when the white noise level is under $40\mu V$ (Avg.) are marked as the hatched area in the graph.

Measurement conditions

Frequency Band: 10Hz to 2MHz

Temperature : $-40^{\circ}C$ to $85^{\circ}C$

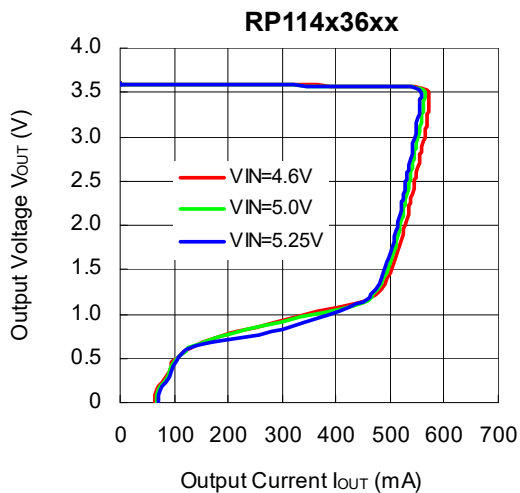
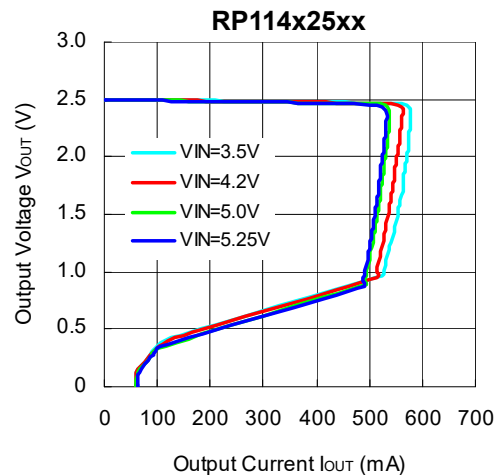
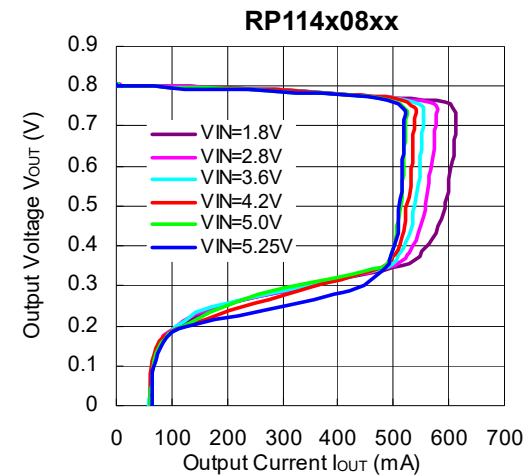
C1, C2 : $1.0\mu F$



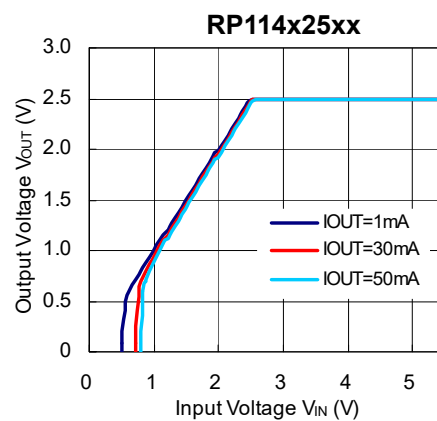
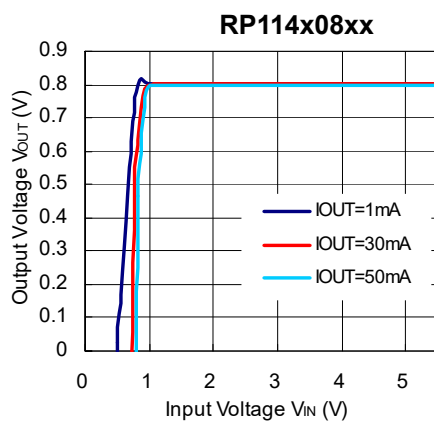
TYPICAL CHARACTERISTICS

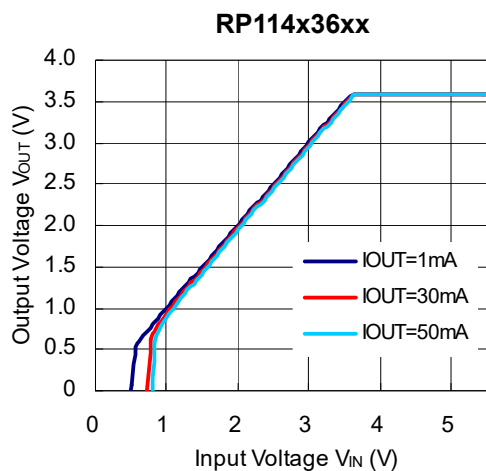
Note: Typical Characteristics are intended to be used as reference data; they are not guaranteed.

1) Output Voltage vs. Output Current ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $T_a=25^\circ\text{C}$)

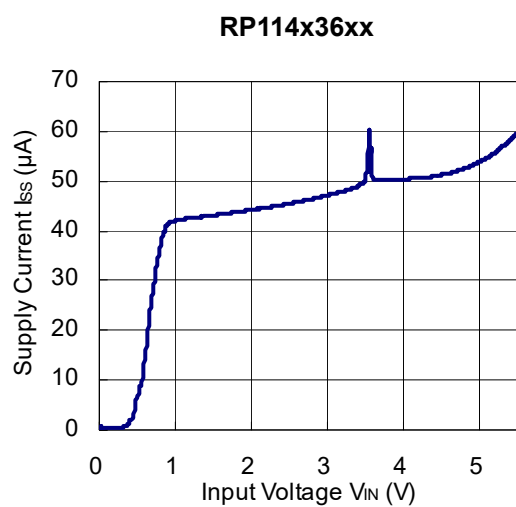
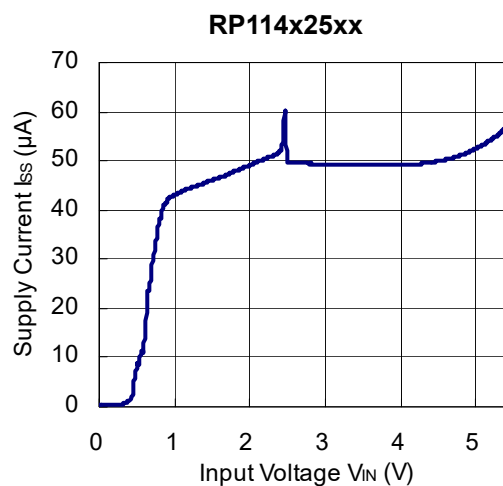
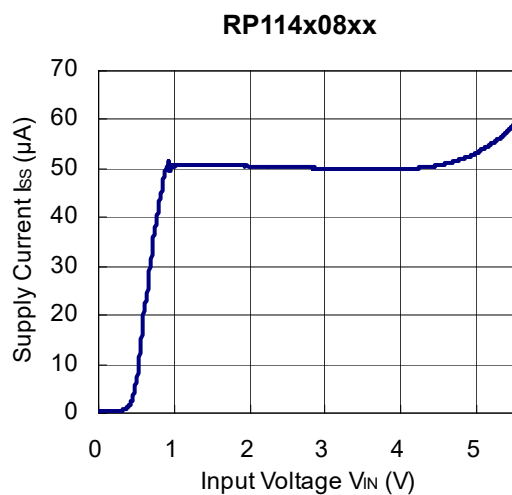


2) Output Voltage vs. Input Voltage ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $T_a=25^\circ\text{C}$)





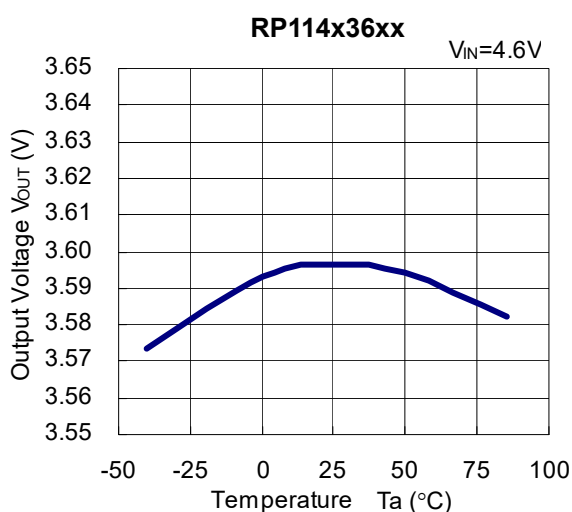
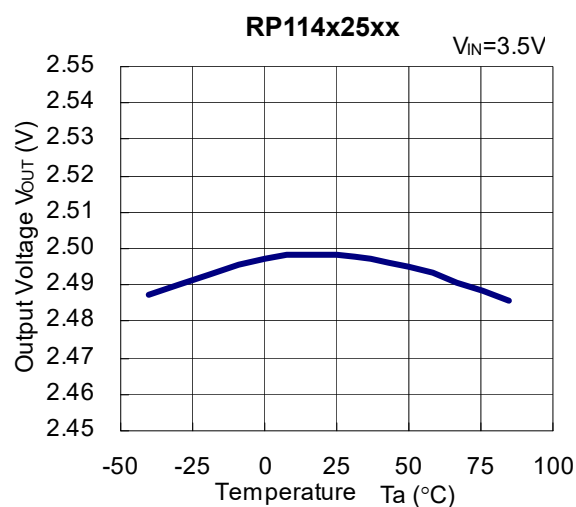
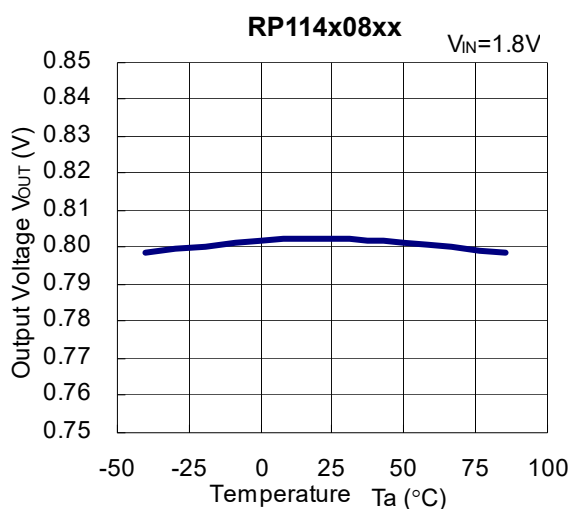
3) Supply Current vs. Input Voltage ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $T_a=25^\circ\text{C}$)



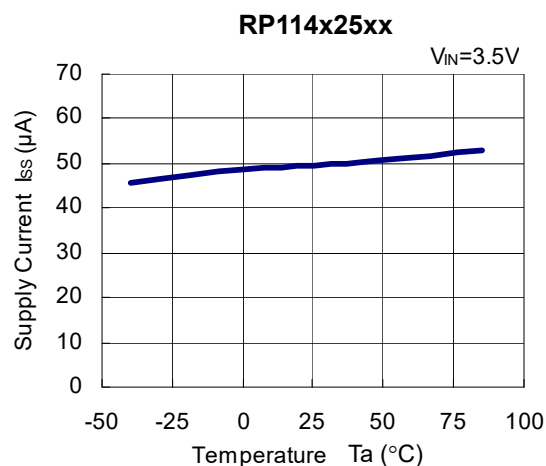
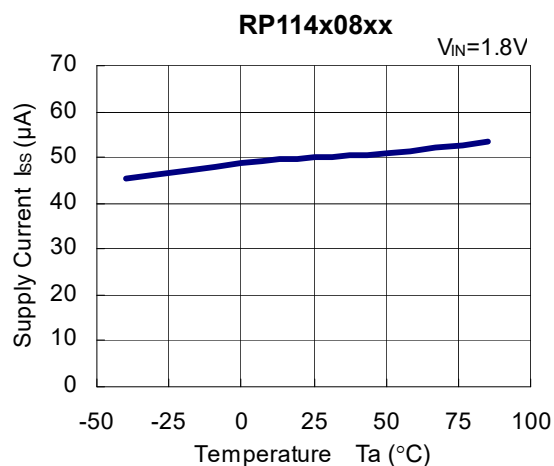
RP114x

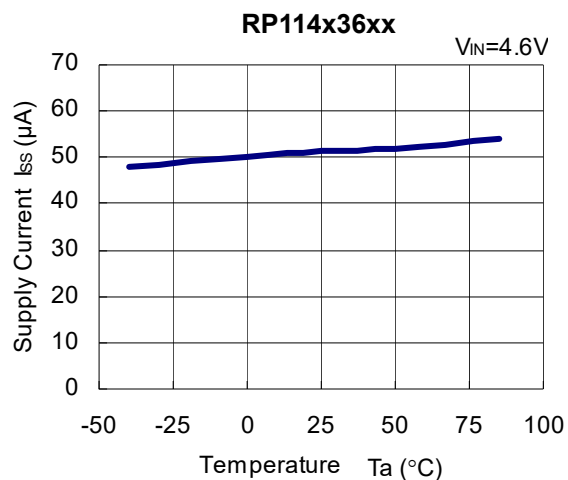
No.EA-236-190130

4) Output Voltage vs. Temperature (C1=1.0 μ F, C2=1.0 μ F, I_{OUT}=1mA)

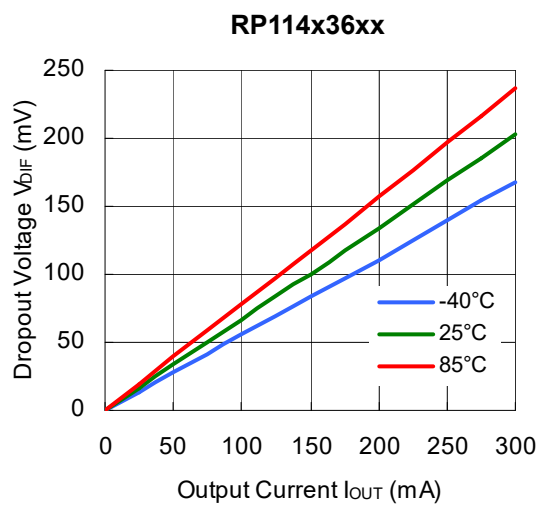
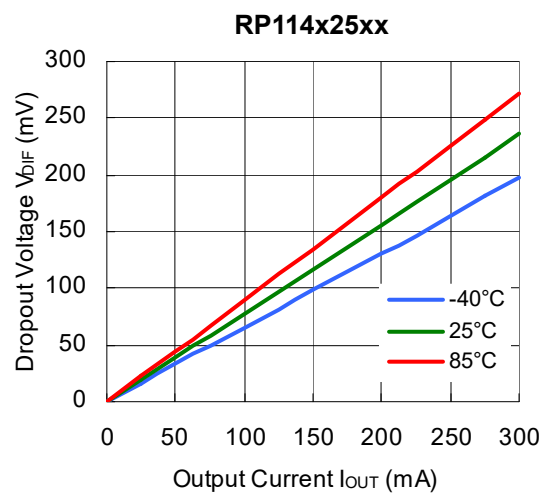
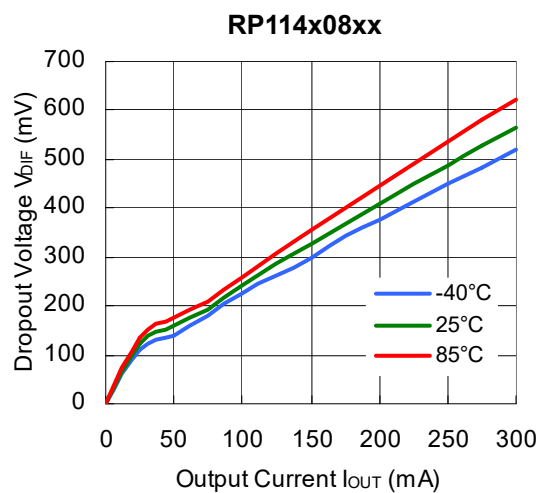


5) Supply Current vs. Temperature (C1=1.0 μ F, C2=1.0 μ F, I_{OUT}=0mA)





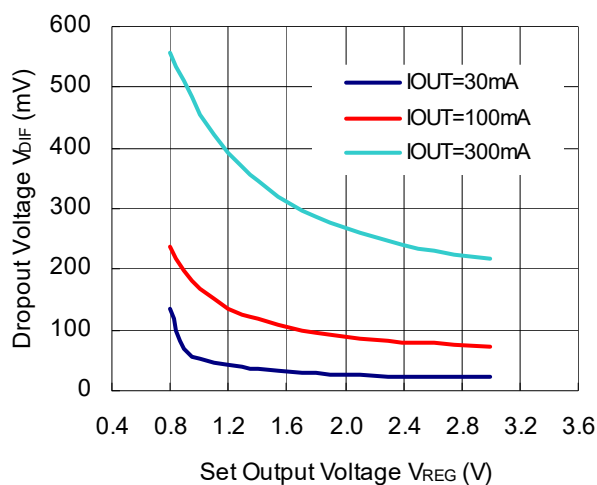
6) Dropout Voltage vs. Output Current ($C1=1.0\mu F$, $C2=1.0\mu F$)



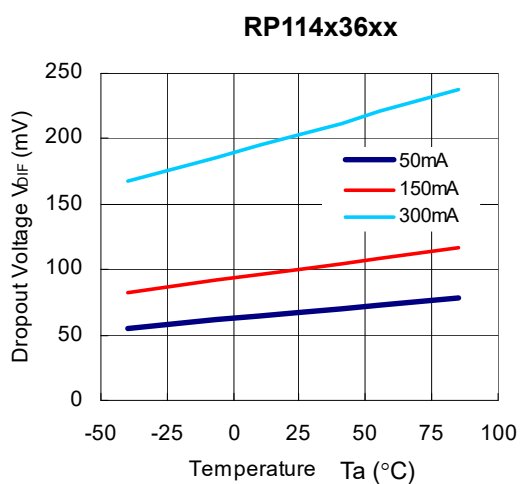
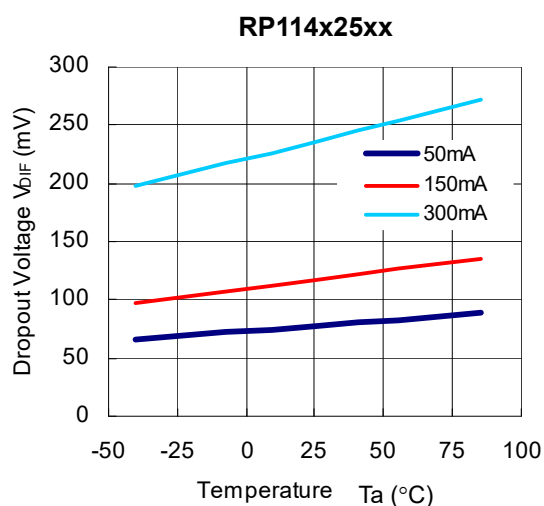
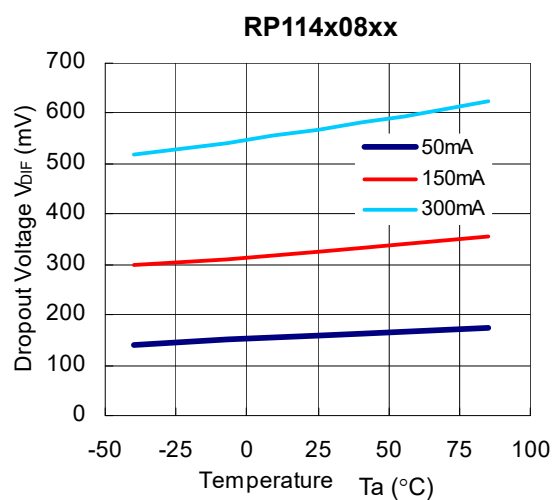
RP114x

No.EA-236-190130

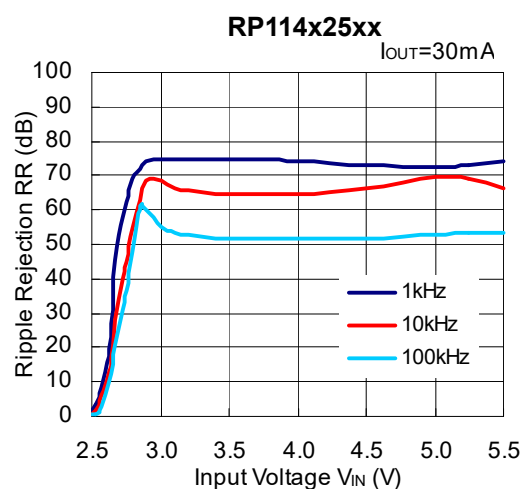
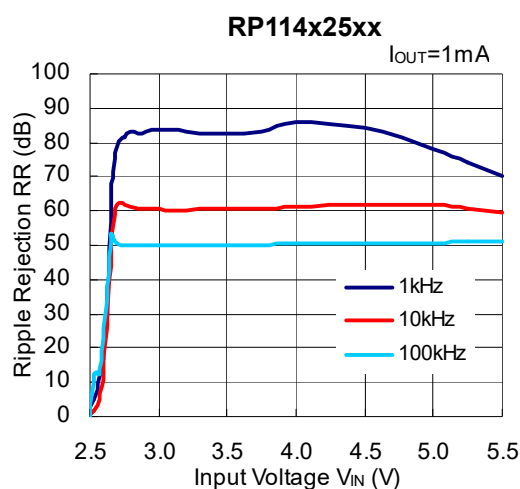
7) Dropout Voltage vs. Set Output Voltage (C1=1.0 μ F, C2=1.0 μ F, Ta=25°C)



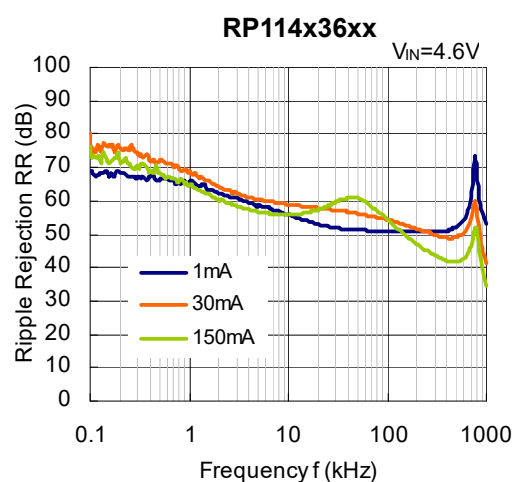
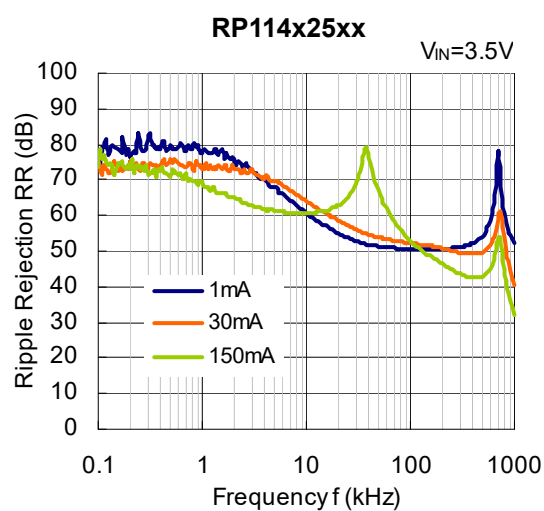
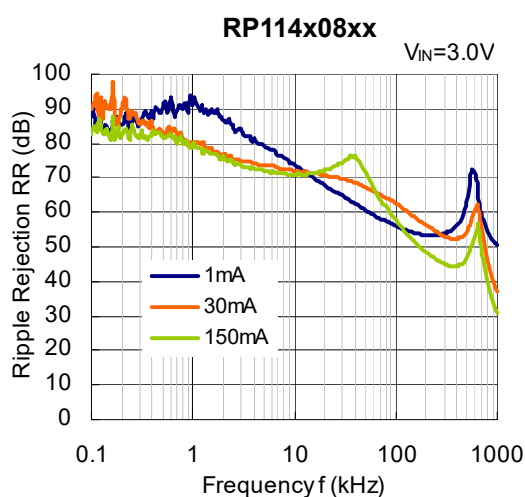
8) Dropout Voltage vs. Temperature (C1=none, C2=1.0 μ F)



9) Ripple Rejection vs. Input Voltage (C1=none, C2=1.0μF, Ripple=0.2Vp-p, Ta=25°C)



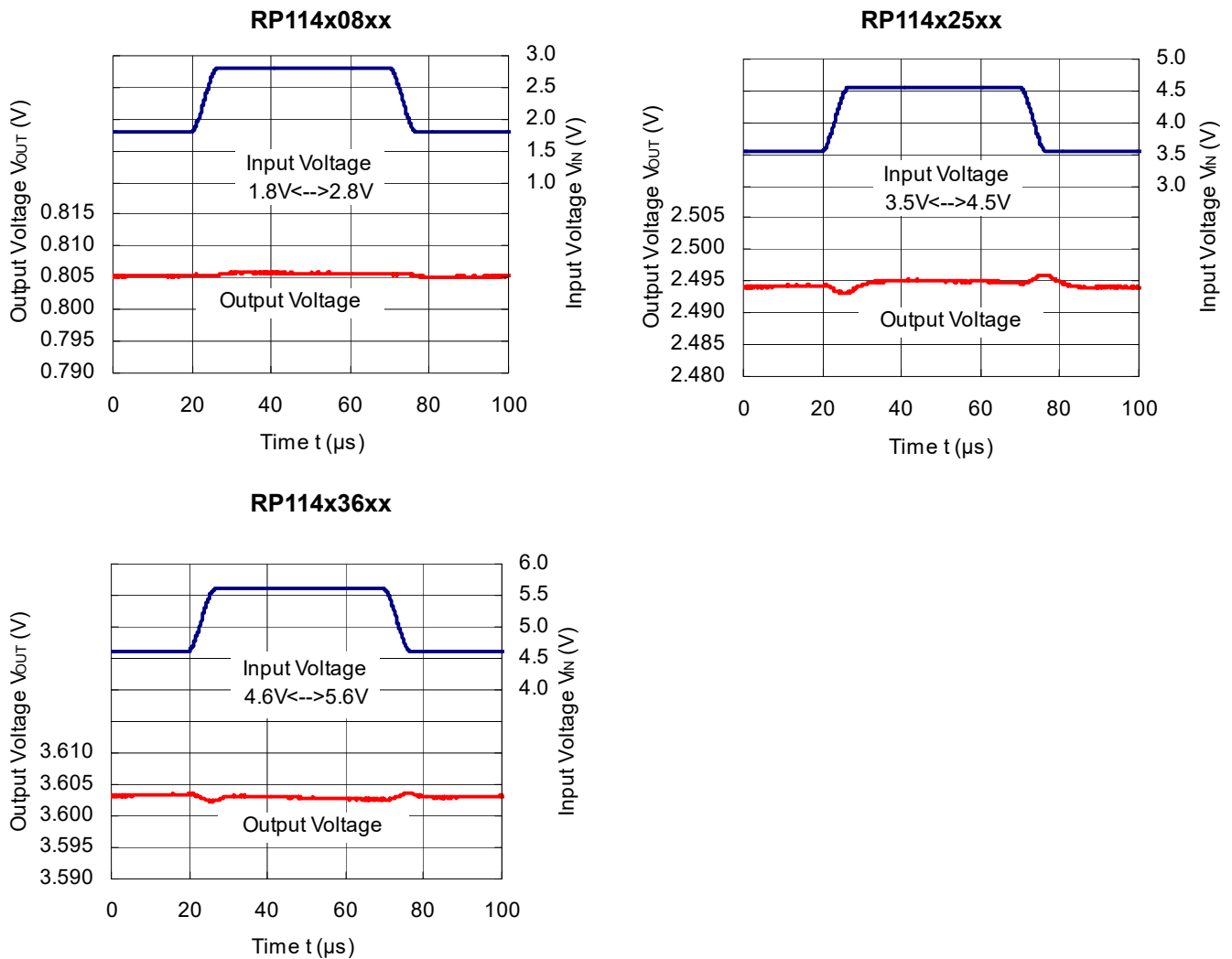
10) Ripple Rejection vs. Frequency (C1=none, C2=1.0μF, Ta=25°C)



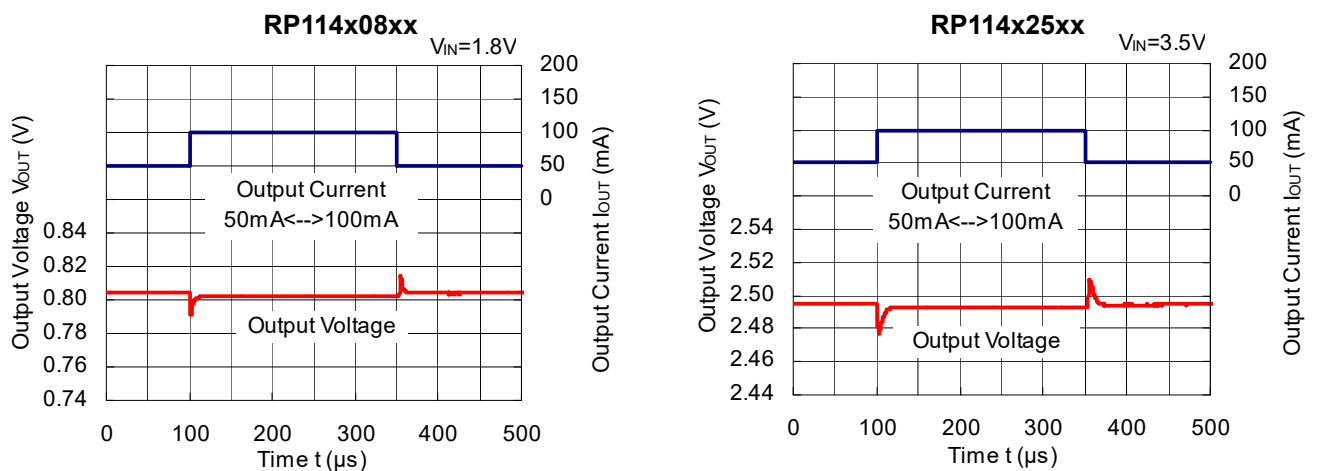
RP114x

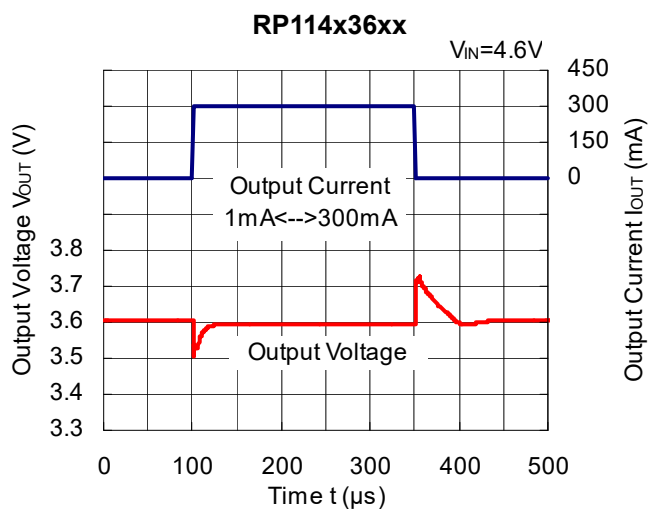
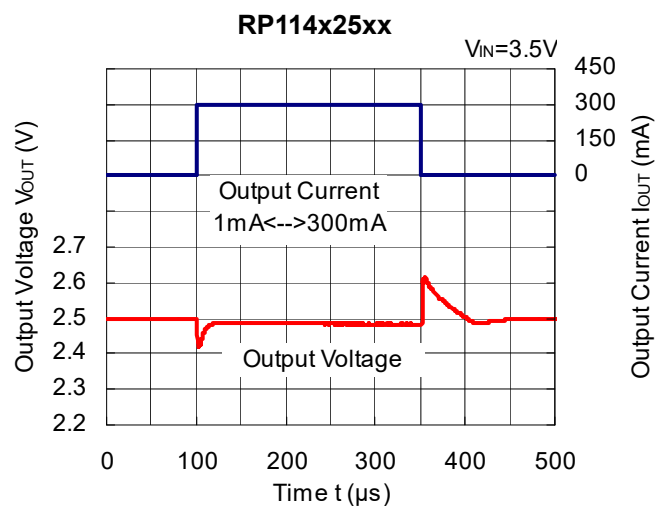
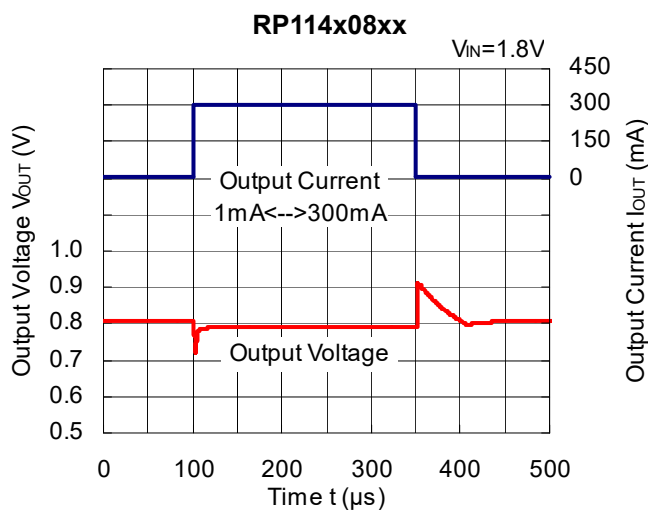
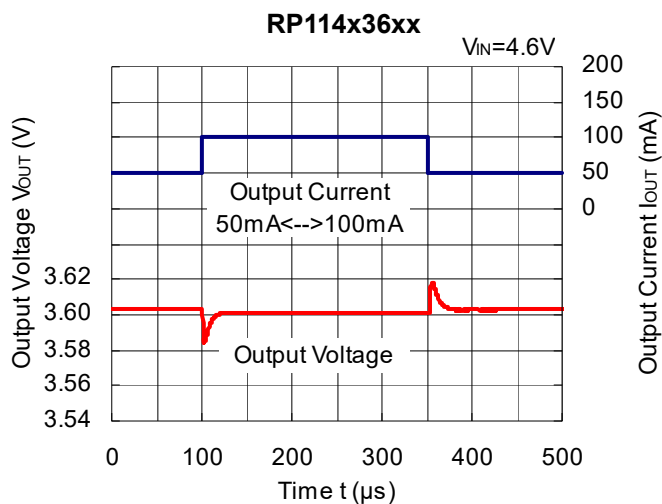
No.EA-236-190130

11) Input Transient Response ($I_{OUT}=30\text{mA}$, $t_r=t_f=5\mu\text{s}$, $T_a=25^\circ\text{C}$)



12) Load Transient Response ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $t_r=t_f=0.5\mu\text{s}$, $T_a=25^\circ\text{C}$)

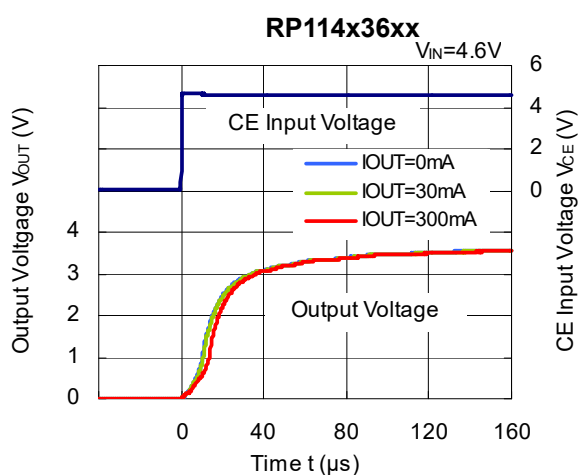
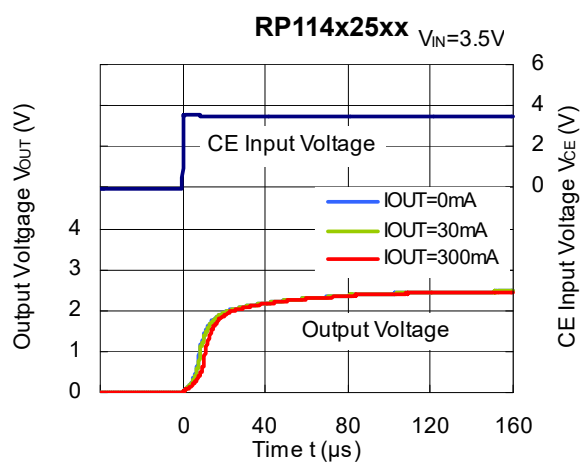
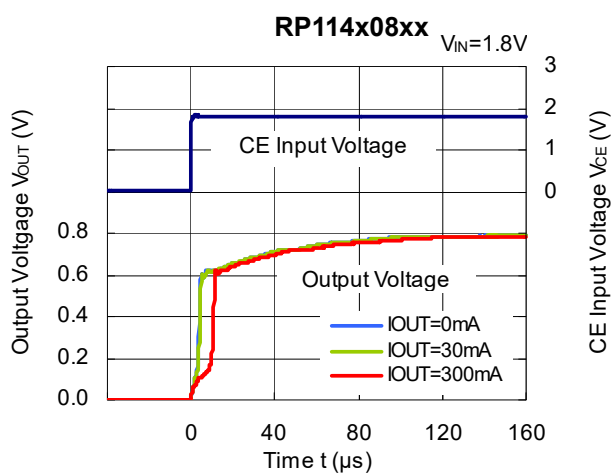




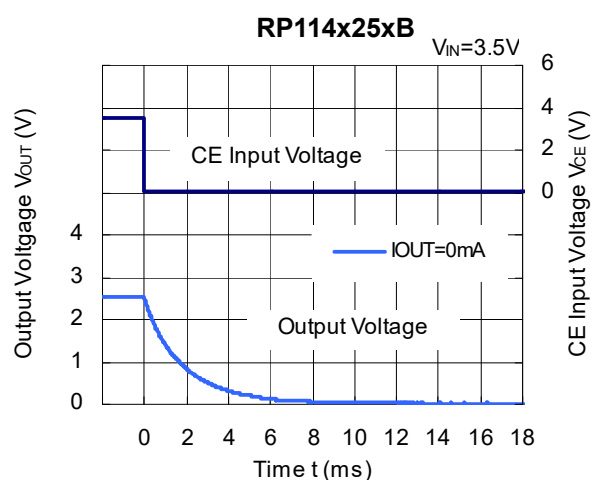
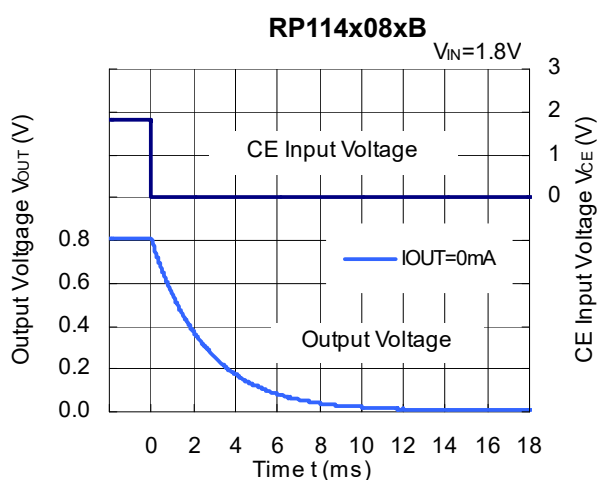
RP114x

No.EA-236-190130

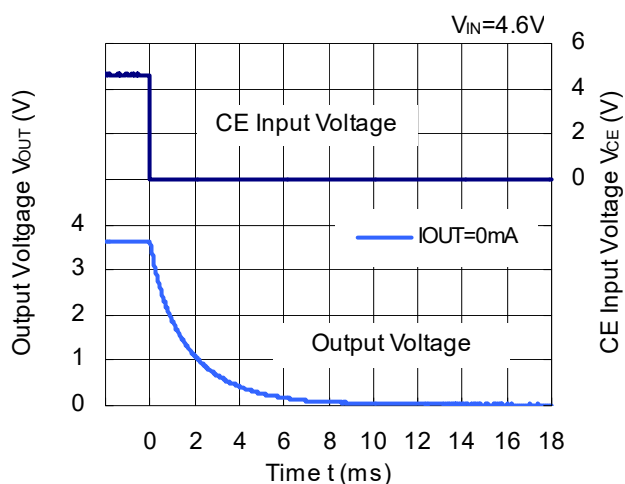
13) Turn On Speed with CE pin ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $T_a=25^\circ\text{C}$)



14) Turn Off Speed with CE pin (B version) ($C_1=1.0\mu\text{F}$, $C_2=1.0\mu\text{F}$, $T_a=25^\circ\text{C}$)

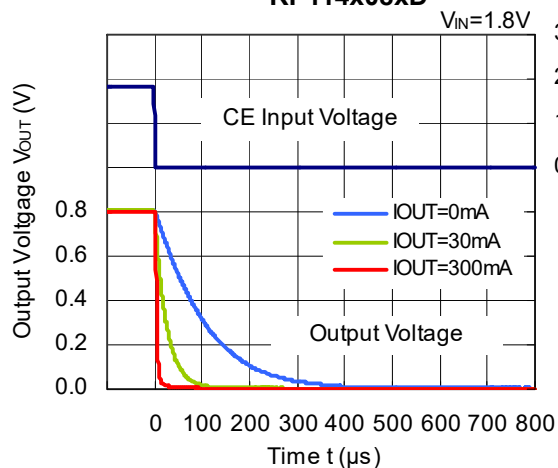


RP114x36xB

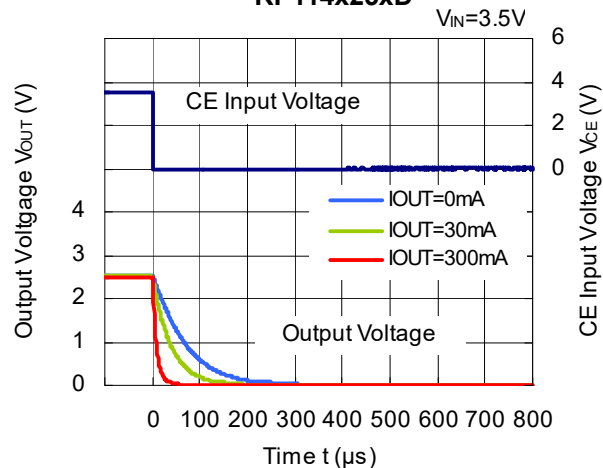


15) Turn Off Speed with CE pin (D version) ($C1=1.0\mu F$, $C2=1.0\mu F$, $T_a=25^\circ C$)

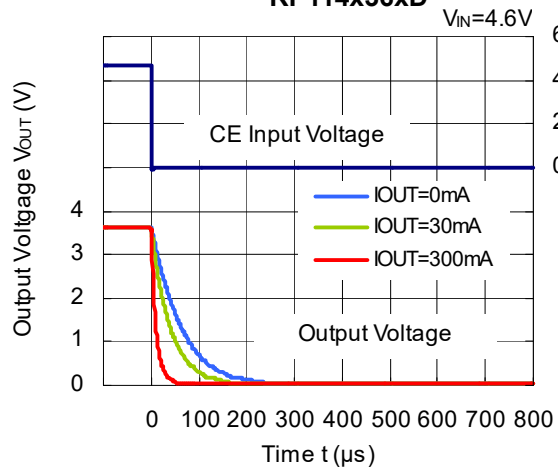
RP114x08xD



RP114x25xD



RP114x36xD



The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

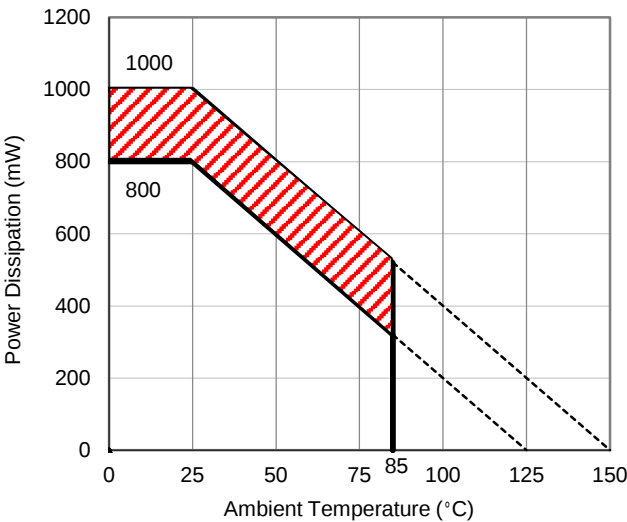
Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.2 mm × 11 pcs

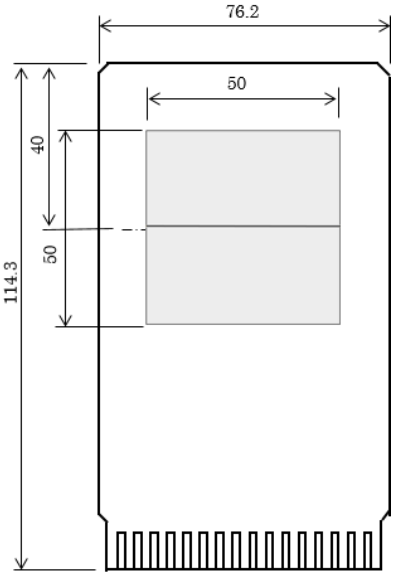
Measurement Result (Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	800 mW
Thermal Resistance (θja)	θja = 125°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 58°C/W

θja: Junction-to-Ambient Thermal Resistance
ψjt: Junction-to-Top Thermal Characterization Parameter



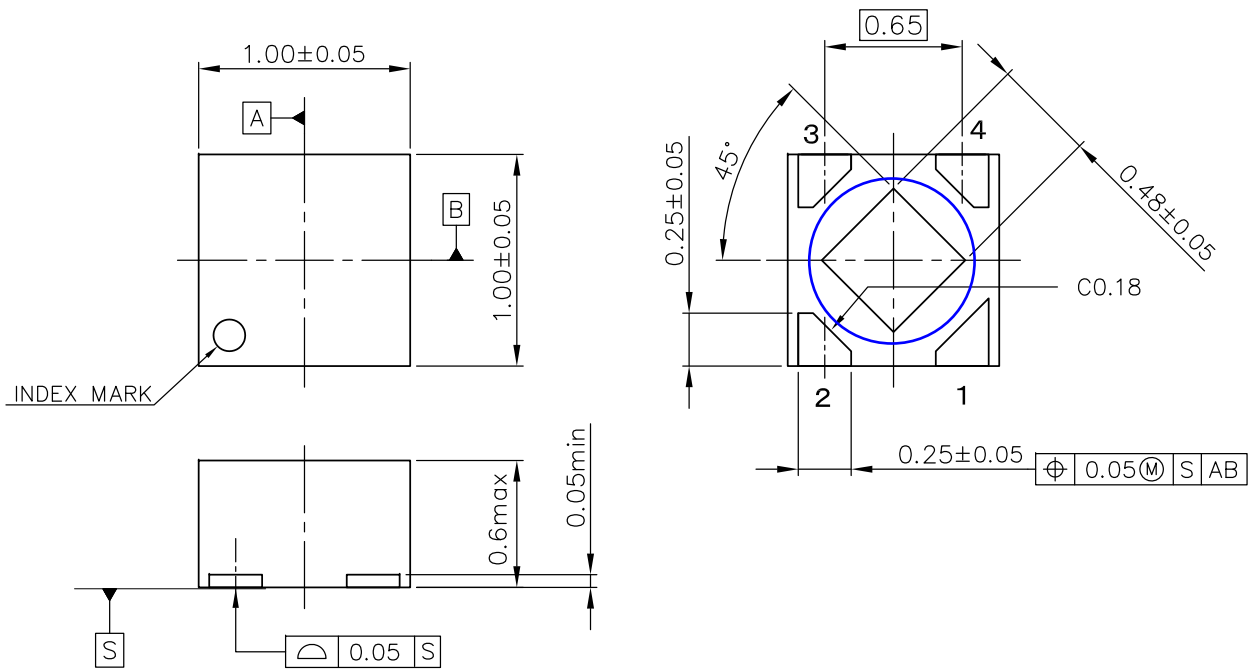
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

The above graph shows the power dissipation of the package at Tjmax = 125°C and Tjmax = 150°C. Operating the device in the hatched range might have a negative influence on its lifetime. The total hours of use and the total years of use must be limited as follows:

Total Hours of Use	Total Years of Use (4 hours/day)
13,000 hours	9 years



UNIT: mm

DFN(PLP)1010-4 Package Dimensions

* The tab on the bottom of the package shown by blue circle is a substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.2 mm × 11 pcs

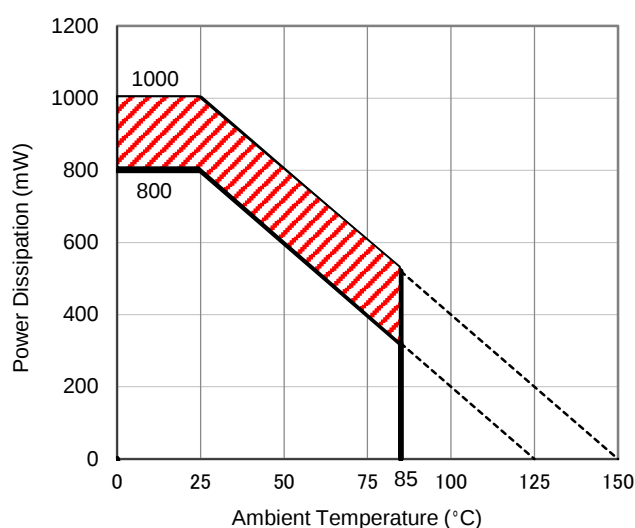
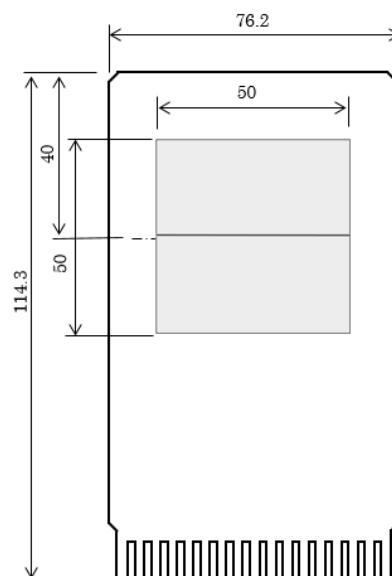
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	800 mW
Thermal Resistance (θ_{ja})	$\theta_{ja} = 125^{\circ}\text{C/W}$
Thermal Characterization Parameter (ψ_{jt})	$\psi_{jt} = 58^{\circ}\text{C/W}$

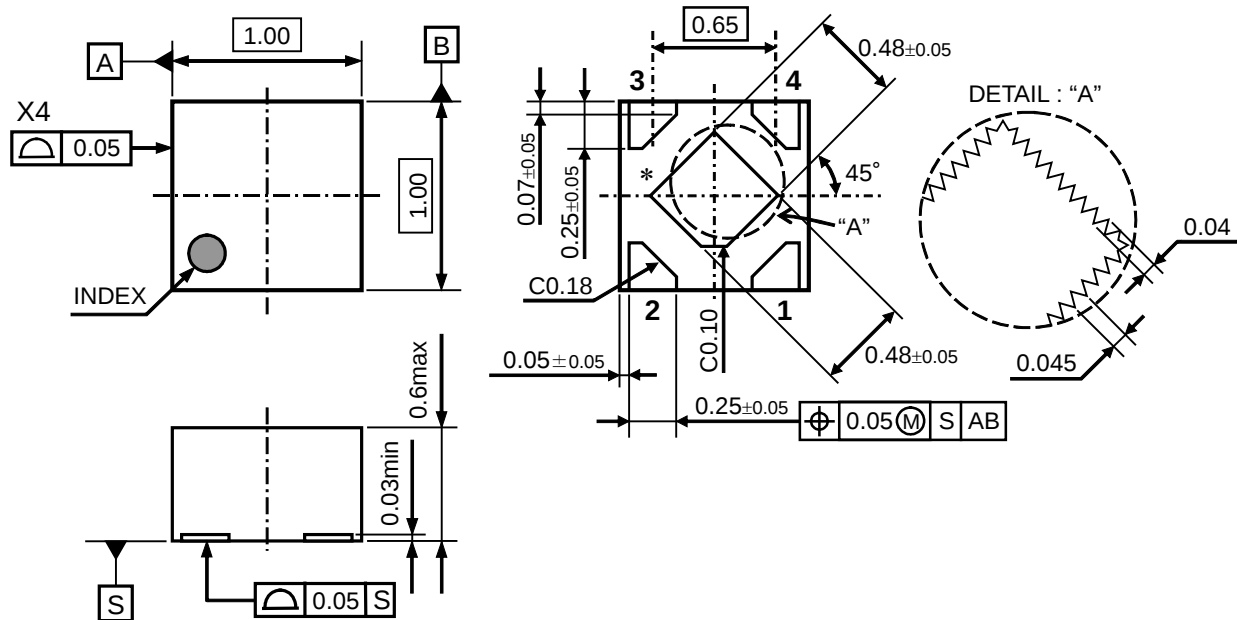
θ_{ja} : Junction-to-Ambient Thermal Resistance

ψ_{jt} : Junction-to-Top Thermal Characterization Parameter

**Power Dissipation vs. Ambient Temperature****Measurement Board Pattern**

The above graph shows the power dissipation of the package at Tjmax = 125°C and Tjmax = 150°C. Operating the device in the hatched range might have a negative influence on its lifetime. The total hours of use and the total years of use must be limited as follows:

Total Hours of Use	Total Years of Use (4 hours/day)
13,000 hours	9 years



DFN (PLP) 1010-4B Package Dimensions (Unit: mm)

* The tab on the bottom of the package is a substrate potential (GND). It is recommended that this tab be connected to the ground plane on the board but it is possible to leave the tab floating.

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following conditions are used in this measurement.

Measurement Conditions

Item	Our Evaluation Board
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Double-Sided Board)
Board Dimensions	40 mm × 40 mm × 1.6 mm
Copper Ratio	Top Side: Approx. 50% Bottom Side: Approx. 50%
Through-holes	φ 0.5 mm × 44 pcs

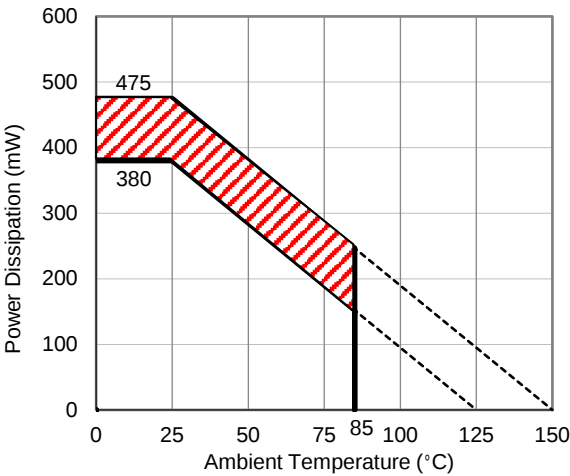
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

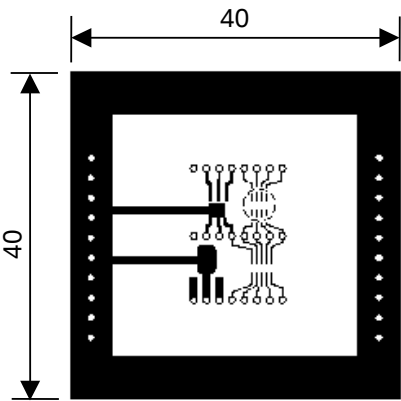
Item	Our Evaluation Board
Power Dissipation	380 mW
Thermal Resistance (θja)	θja = 263°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 75°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter



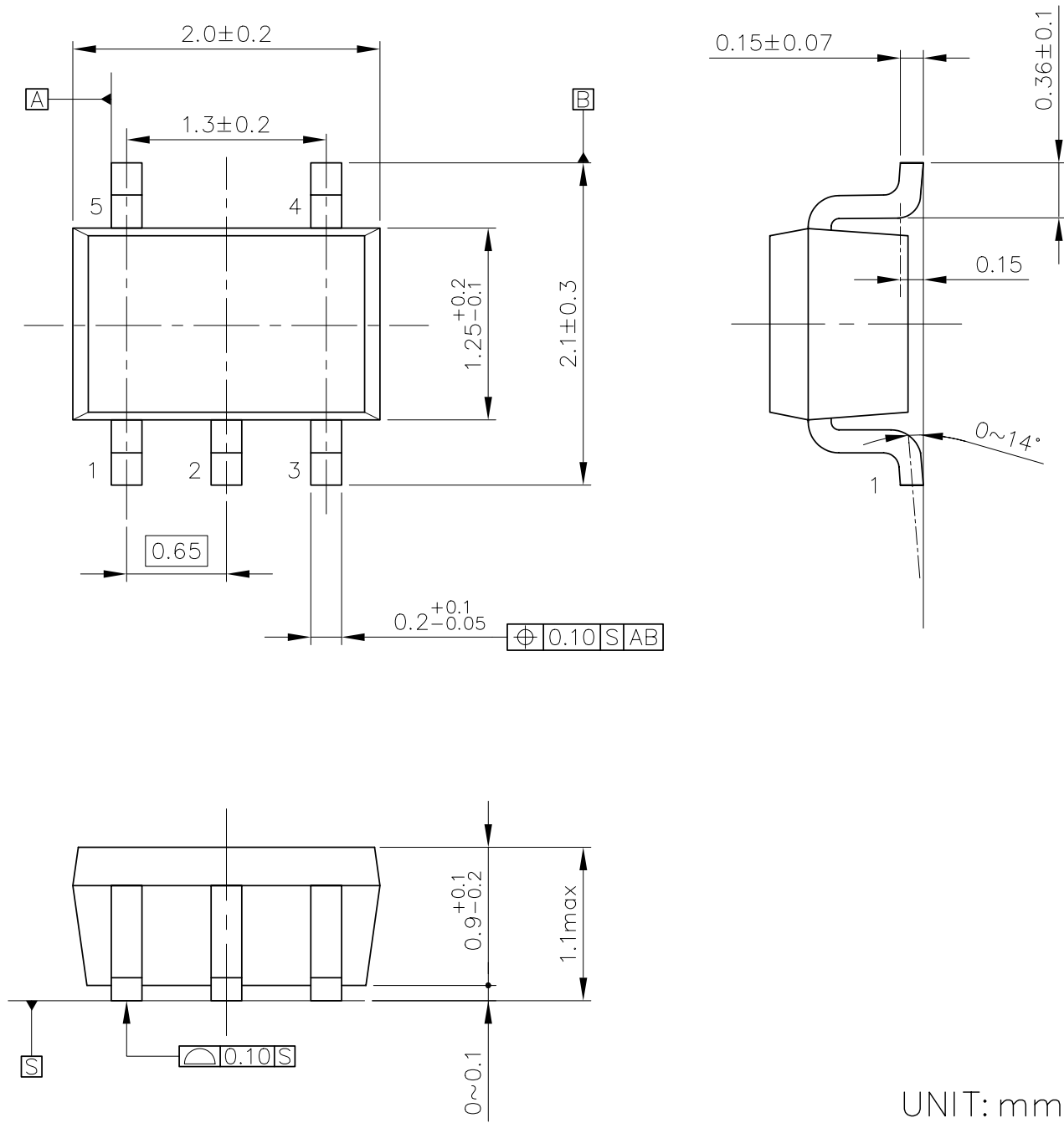
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

The above graph shows the power dissipation of the package at Tjmax = 125°C and Tjmax = 150°C. Operating the device in the hatched range might have a negative influence on its lifetime. The total hours of use and the total years of use must be limited as follows:

Total Hours of Use	Total Years of Use (4 hours/day)
13,000 hours	9 years



SC-88A Package Dimensions

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

Item	Measurement Conditions
Environment	Mounting on Board (Wind Velocity = 0 m/s)
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square
Through-holes	φ 0.3 mm × 7 pcs

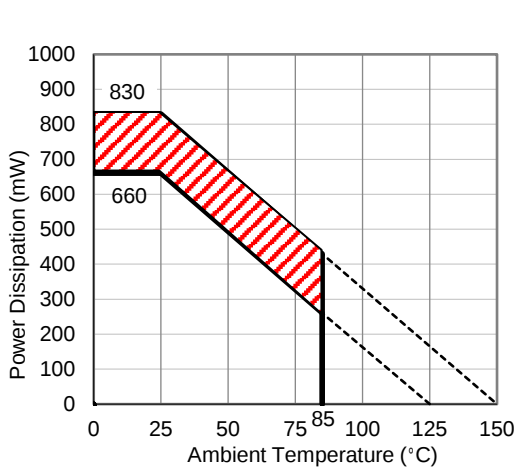
Measurement Result

(Ta = 25°C, Tjmax = 125°C)

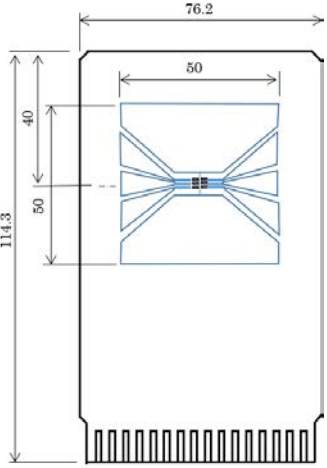
Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

θja: Junction-to-Ambient Thermal Resistance

ψjt: Junction-to-Top Thermal Characterization Parameter



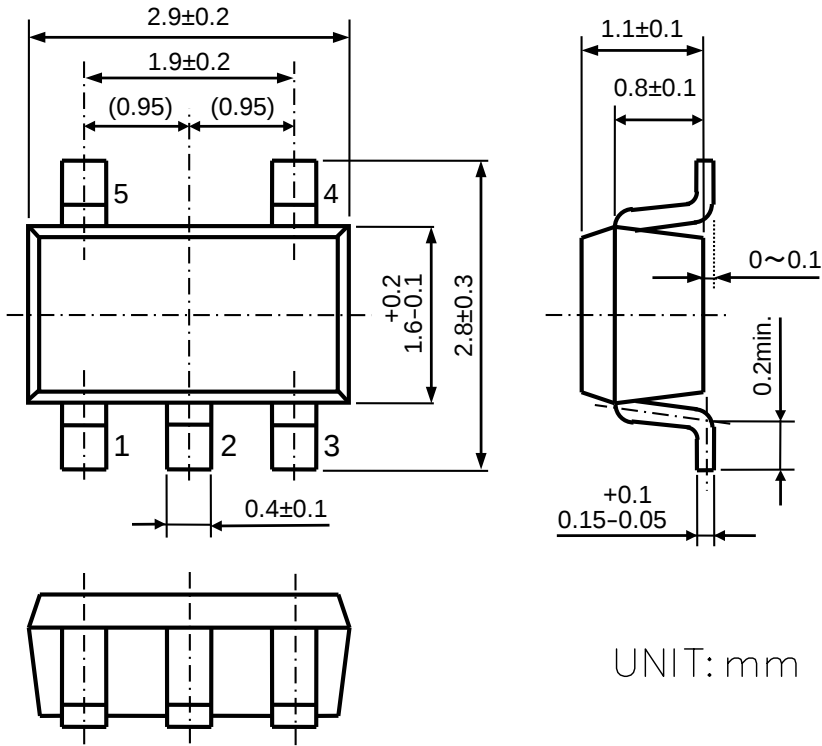
Power Dissipation vs. Ambient Temperature



Measurement Board Pattern

The above graph shows the power dissipation of the package at Tjmax = 125°C and Tjmax = 150°C. Operating the device in the hatched range might have a negative influence on its lifetime. The total hours of use and the total years of use must be limited as follows:

Total Hours of Use	Total Years of Use (4 hours/day)
13,000 hours	9 years



SOT-23-5 Package Dimensions



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